

Modeling Optimization Problems: Case Study

GIAN Short Course on Optimization: Applications, Algorithms, and Computation

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Outline

- 1 Modeling Optimization Problems: Case Study
- 2 First Model of Thermal Insulation
- 3 Building an AMPL Model



Modeling Optimization Problems: Case Study

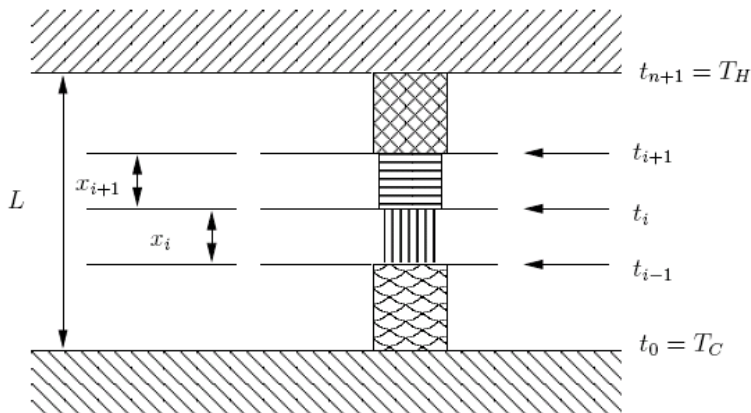
Goal of our case study

- Work through concrete optimization example
 - Show interplay between variables & constraints
 - Build model **from physics to math**
... or from words to equations
 - Real physical design problem
- Highlight some modeling tricks
... preview of mixed-integer optimization part
- Continue our exploration of AMPL
- **Show how good modeling improves solvability**

Original model by Abramson (2004) modified by Abhishek et al. (2008)



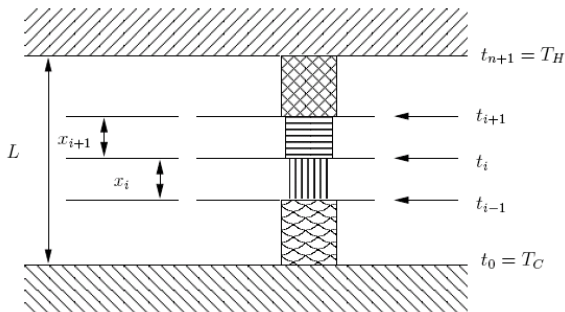
Design of Load-Bearing Thermal Insulation System



Description of System

Insulation system uses series of heat intercepts to reduce heat from hot (top) to cold (bottom) surface

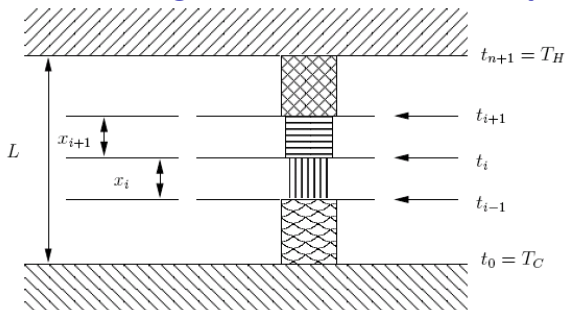
Design of Load-Bearing Thermal Insulation System



- Similar to system used in Large Hadron Collider (LHC)
- Must be good insulator **and** support weight
- Uses insulation properties and cooling between layers (intercepts)
- Choose thickness of layers, **and material type** of layer
- Also **optimize number of layers**



Design of Load-Bearing Thermal Insulation System



Design Goal or Objective

Minimize **cooling power** needed to run system

- Active cooling at intercepts between layers \Rightarrow **cooling power**
- Given hot surface temperature, maintain cold surface temperature below allowable maximum

1D layers \Rightarrow no heat equation: $u_t - \Delta u = g \dots$ effects small

Outline

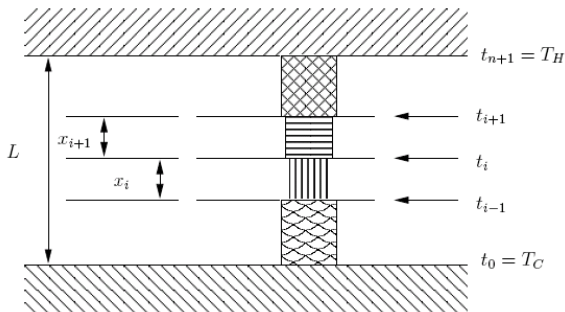
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Discrete Design Variables Overview

Discrete design variables over which we optimize

- Number of intercepts, $n \in \{1, 2, \dots, N = 10\}$ discrete
- m_i material $m_i \in \mathcal{M}$ of insulator $i = 1, \dots, n + 1$
where $m_i \in \mathcal{M} = \{ \text{nylon, teflon, epoxy-normal, epoxy-plane, aluminium, steel, carbon-steel} \}$... discrete choice



Continuous Design Variables Overview

Continuous variables over which we optimize

- x_i length of insulator $i = 1, \dots, n + 1$
- a_i area of insulator $i = 1, \dots, n + 1$
- q_i heat flow from intercept i to $i - 1$, for $i = 1, \dots, n + 1$
- t_i cooling temperature at intercept $i = 0, \dots, n + 1$
- Δx_i thermal expansion of layer $i = 1, \dots, n + 1$
can be eliminated later

where layers 0 and $n + 1$ are cold and hot surface, respectively

- Cold surface temperature is $t_0 = T_C = 4.3\text{K}$ (near abs. zero)
- Hot surface temperature is $t_n = T_H = 300\text{K}$ (27C)



Objective Function

Minimize cooling power (**discontinuous** ... reformulate later)

$$\text{minimize } \sum_{i=1}^n C(t_i) \left(\frac{T_H}{t_i} - 1 \right) \cdot (q_{i+1} - q_i)$$

where

- $C(t_i)$ thermodynamic cycle efficiency of intercept i

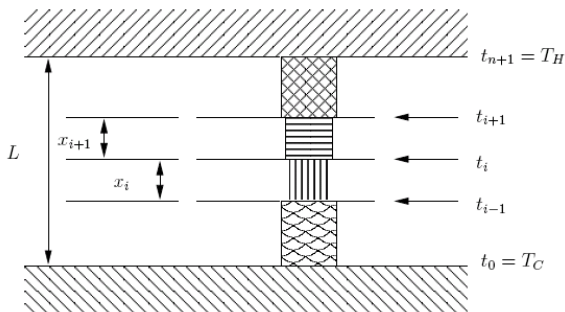
$$C(t_i) = \begin{cases} 5 & \text{if } t_i \leq 4.2, \\ 4 & \text{if } 4.2 < t_i < 71, \\ 2.5 & \text{if } t_i \geq 71. \end{cases} \quad i = 1, \dots, n$$

- t_i is cooling temperature at intercept i
- q_i is heat flow from intercept i
- $T_H=27\text{C}$ is ambient temperature $\Rightarrow \frac{T_H}{t_i} \geq 1$



Simple Linear Constraints

- $\sum_{i=1}^n x_i = L$ insulator thickness add up to L , length
- $t_{i-1} \leq t_i \leq t_{i+1}$, $i = 1, \dots, n$ ordered cooling temperatures
- $t_0 = T_C = 4.3\text{K}$ & $t_{n+1} = T_H = 300\text{K}$ fixed cold & hot temps
- $1 \leq n \leq N$ integer number of layers
- $x_i \geq 0$, & $a_i \geq 0$, $i = 1, \dots, n + 1$ nonnegative thickness & area



Modeling Heat Transfer q_i

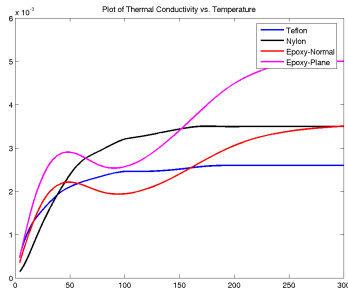
Given t_{i-1} , t_i , heat transfer from **Fourier's law**

$$q_i = \frac{a_i}{x_i} \int_{t_{i-1}}^{t_i} k(t, m_i) dt$$

where a_i area, x_i thickness of intercept i

Model of thermal conductivity

- $k(t, m_i)$ thermal conductivity of insulator m_i at temperature t
- $k(t, m_i)$ given as **tabulated data**
- interpolate using cubic splines
- integration with Simpson's rule
⇒ consistent with cubic splines



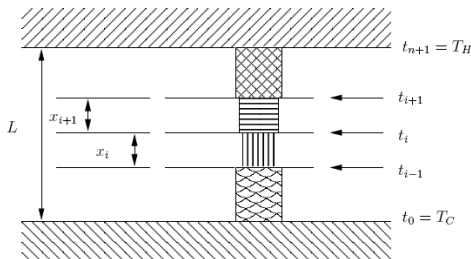
Modeling the Mass Constraint

Constraint on total mass of system:

$$\sum_{i=1}^n \rho(m_i) a_i x_i \leq M$$

where

- a_i area, x_i thickness of intercept i
- $\rho(m_i)$ is density of material m_i



Stress Limit Constraint

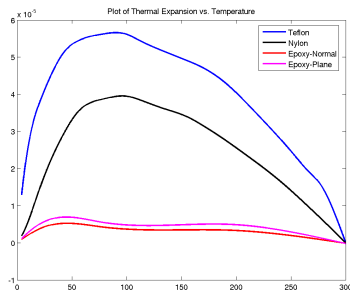
Stress of insulator i must not exceed load F

$$\frac{F}{a_i} \leq \bar{\sigma}_i = \min \{ \sigma(t, m_i) : t_{i-1} \leq t \leq t_i \}$$

where

- $\sigma(t, m_i)$ tensile yield strength of insulator m_i at temp. t
- $\sigma(t, m_i)$ given as tabulated data
- interpolated using cubic splines
- write as **semi-infinite constraint**

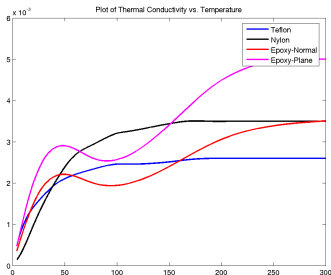
$$\Leftrightarrow \frac{F}{a_i} \leq \sigma(t, m_i) \quad \forall t : t_{i-1} \leq t \leq t_i$$



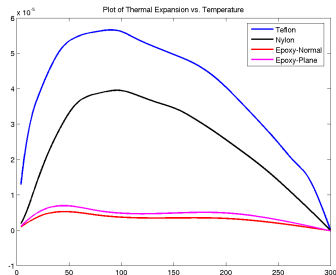
Teaching Point: Modeling Discrete Decisions

Materials { nylon, teflon, epoxy-normal, epoxy-plane, aluminium, steel, carbon-steel } are **not linearly ordered**

⇒ cannot assign numbers 1, ... 7



Thermal Conductivity



Yield Strength



Modeling Thermal expansion of layers

Layers cannot expand more than δ %:

$$\sum_{i=1}^n \left(\frac{\Delta x_i}{x_i} \right) \left(\frac{x_i}{L} \right) \leq \frac{\delta}{100} \quad \Leftrightarrow \quad \sum_{i=1}^n u_i x_i \leq L \frac{\delta}{100}$$

where u_i relative expansion, replaces Δx_i .

Physical model of thermal expansion

$$\frac{\Delta x_i}{x_i} = u_i = \frac{\int_{t_{i-1}}^{t_i} e(t, m_i) k(t, m_i) dt}{\int_{t_{i-1}}^{t_i} k(t, m_i) dt}, \quad i = 1, \dots, n$$

from thermal conductivity, $k(t, m_i)$, and yield strength, $e(t, m_i)$

Why did we introduce u_i ?



Teaching Point: Spread the Nonlinearities

Why did we introduce u_i ? Consider new variables, r, v, w

$$\left(\frac{r}{v}\right) \left(\frac{v}{L}\right) \leq D \quad \text{and} \quad \left(\frac{r}{v}\right) = \frac{f(r, v, w)}{g(r, v, w)}$$

where $f(r, v, w), g(r, v, w)$ nonlinear functions, L, D constants

Clearly, can simplify 1st constraint to $r \leq LD$

- Makes 1st constraint linear
- Keeps $\frac{r}{v}$ in 2nd constraint

By introducing $u = \frac{r}{v}$, we “spread the nonlinearity”

$$uv \leq LD \quad \text{and} \quad u = \frac{f(r, v, w)}{g(r, v, w)}$$

Best formulation depends on model ... no general rules!



Complete Mixed Variable Model

minimize $\sum_{i=1}^n C_i(t_i) \left(\frac{T_H}{t_i} - 1 \right) \cdot (q_{i+1} - q_i)$ cooling power

subject to $q_i = \frac{a_i}{x_i} \int_{t_{i-1}}^{t_i} k(t, m_i) dt$ heat transfer

$$\sum_{i=1}^n \rho(m_i) a_i x_i \leq M$$

total mass

$$F \leq a_i \sigma(t, m_i) \quad \forall t : t_{i-1} \leq t \leq t_i$$

stress limit

$$\sum_{i=1}^n u_i x_i \leq L \frac{\delta}{100}$$

thermal expansion

Plus linear constraints: $t_{i-1} \leq t_i \leq t_{i+1}$, $x_i \geq 0$, $a_i \geq 0$

$$\sum_{i=1}^n x_i = L, \quad t_0 = T_C, \quad t_{n+1} = T_H, \quad n \in \{1, \dots, N\}, \quad m_i \in \mathcal{M}$$



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Exam: Code this Model in AMPL

Great model, let's see what the AMPL code looks like ...



Exam: Code this Model in AMPL

Great model, let's see what the AMPL code looks like ...

Are you kidding me??? This won't work in AMPL!!!

- How do I encode the material choice, **which is non-integer?**

$$m_i \in \mathcal{M} = \{\text{nylon, teflon, epoxy-normal, ... steel, carbon-steel}\}$$

- How can I have **variables as limits in summations?**

$$\sum_{i=1}^n x_i = L, \quad n \in \{1, \dots, N = 10\}$$

Would be written in AMPL as

```
param N := 10;           # ... max. number of layers
param L := 10;           # ... system length [cm]
var n, integer, >=1, <=N; # ... number of layers
var x{1..n} >= 0;        # ... length of layer
subject to
    Length: sum{i in 1..n} x[i] = L;
```

Creates at least two ERRORS ... where?



Exam: Code this Model in AMPL

How can I have **variables as limits in summations**?

$$\sum_{i=1}^n x_i = L, \quad n \in \{1, \dots, N = 10\}$$

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subject to
    Length: sum{i in 1..n} x[i] = L;
```

Creates at least two ERRORS ... where?

- Variable n cannot be set limiter

```
var x{1..n} >= 0;           # ... length of layer
```

- Variable n cannot be summation limiter

```
Length: sum{i in 1..n} x[i] = L;
```



Other Issues with Our Model

- Even if AMPL allowed variable n as summation limit ... problem is discontinuous ... **sum only defined for integers**
- Objective function (cooling power) is **discontinuous**

$$\text{minimize } \sum_{i=1}^n C_i(t_i) \left(\frac{T_H}{t_i} - 1 \right) \cdot (q_{i+1} - q_i)$$

because

$$C(t_i) = \begin{cases} 5 & \text{if } t_i \leq 4.2, \\ 4 & \text{if } 4.2 < t_i < 71, \\ 2.5 & \text{if } t_i \geq 71. \end{cases} \quad i = 1, \dots, n$$

... **most AMPL solvers require smooth functions**



Other Issues with Our Model

Evaluation of heat transfer integrals requires quadrature

$$q_i = \frac{a_i}{x_i} \int_{t_{i-1}}^{t_i} k(t, m_i) dt$$

- Can in principle “code” quadrature rules in AMPL
- Resulting would be highly nonlinear,
because integrals depend on variable t_i
- AMPL is an interpretive **not compiled** language
⇒ quadrature rules would make function evaluation inefficient



Towards an AMPL Model

How do we solve this pesky problem?

- Code functions in Fortran or C/C++
⇒ efficient function evaluations
- No derivatives, consider derivative-free solvers, e.g. pattern-search, simulated annealing, or evolutionary algorithms

Snag: Solver loses model insight ... black-box optimization

Can we still use AMPL to solve this model?

- Requires some modeling tricks
- Resulting model is a **smooth mixed-integer nonlinear program**
- Efficient ... optimum 10% better than derivative-free solvers



Conclusion and Outlook

Introduced a challenging case study

- Design of thermal insulation layer for LHC
 - Goal is to minimize cooling energy
 - Constraints on thermal insulation, mass, stress limits
 - **Discrete design choices: number of layers, material**
 - Continuous design parameters: thickness, area, temperature
- Translated physical description into mathematical model
- Numerically challenging problem ... **no obvious AMPL model**
- Integer modeling tricks (next week) make it tractable

Return to model later, when we learn about integer variables

